

IN RE APPLICATION OF:

Shigeo KOUZUKI, et al.

SERIAL NO: 10/020,928

FILED: 12/19/01

FOR: SEMICONDUCTOR DEVICE AND PACKAGE THEREFOR

LETTER TO THE OFFICIAL DRAFTSMAN

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, DC 20231

SIR:

In response to the Notice to File Missing Parts of Nonprovisional Application, attached hereto please find 9 sheets of Substitute Formal Drawings. It is requested that the enclosed 9 sheets of Substitute Formal Drawings be entered to replace the drawings previously filed in this application.

Respectfully submitted,

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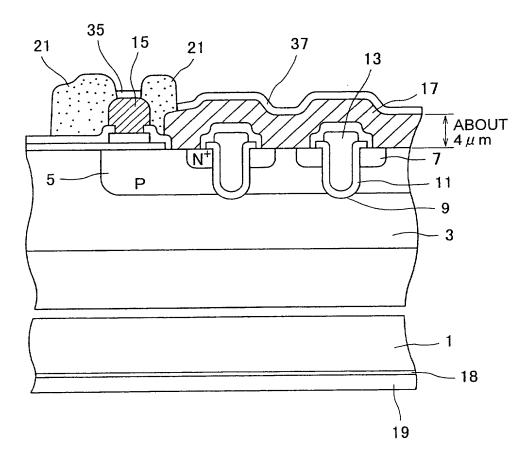
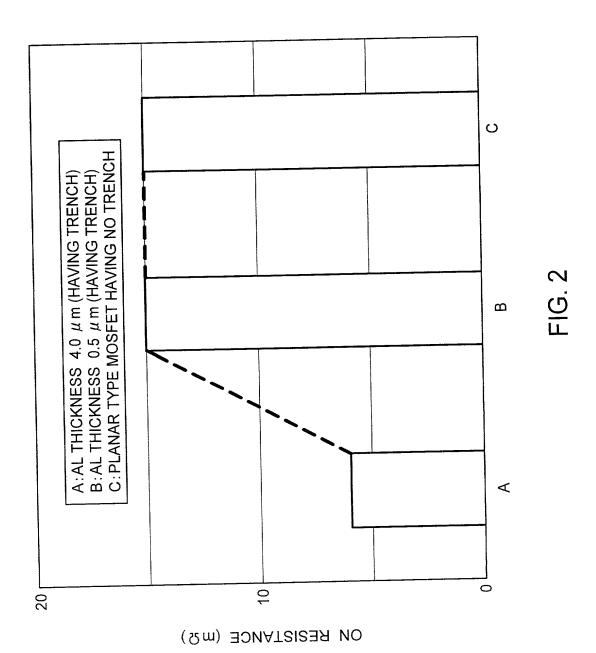


FIG. 1





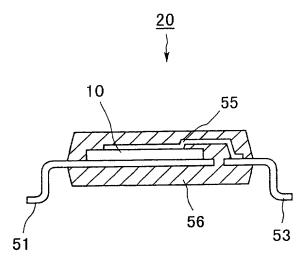


FIG. 3A

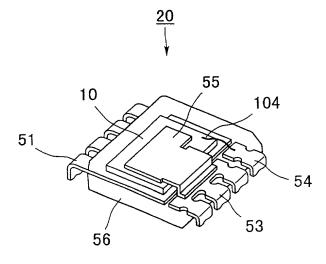


FIG. 3B



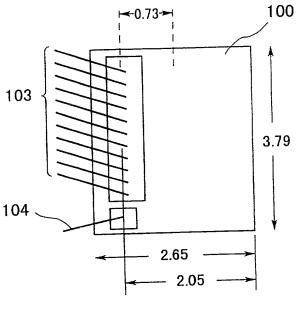
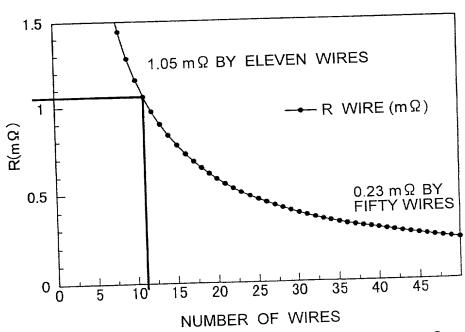


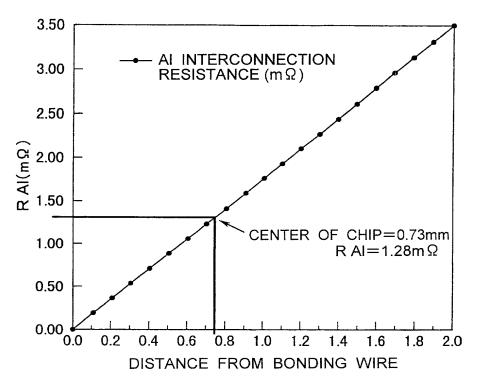
FIG. 4



R Au WIRE VS NUMBER OF WIRES (ϕ 60 μ m, 2mm)

FIG. 5

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AI INTERCONNECTION RESISTANCE ON SURFACE OF CHIP

FIG. 6





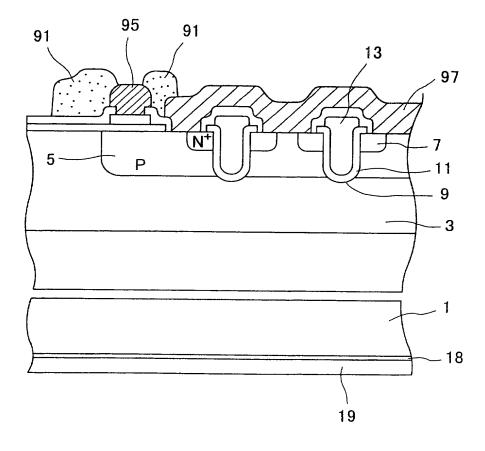


FIG. 7

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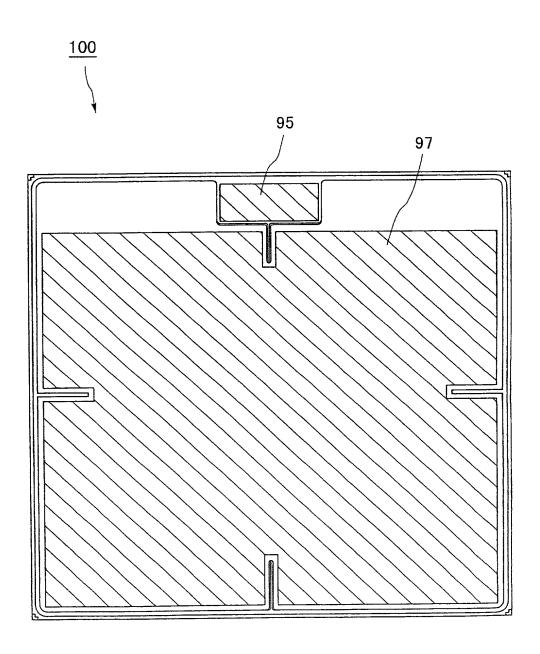


FIG. 8



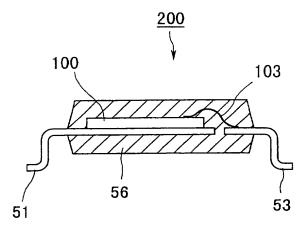


FIG. 9A

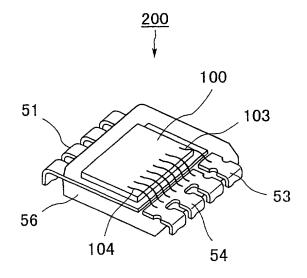


FIG. 9B



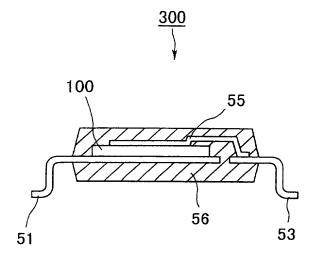


FIG. 10A

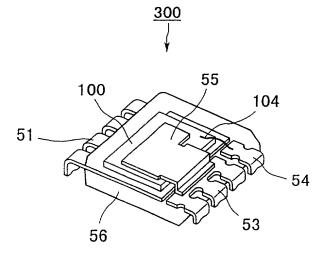


FIG. 10B